



EUROPRACTICE
IC SERVICE

TSMC 0.18μ, 0.13μ - 90nm, 65nm, 40nm & 28nm CMOS

IMEC and TSMC agree to offer Multi Project Wafer Services and small volume production in deep submicron CMOS technologies through the EUROPRACTICE IC Service

Features and Benefits

- Cost reduction on prototypes
- Monthly or regular MPW runs
- Flexible access to silicon capacity for small volumes at TSMC
- Deep Submicron RTL-to-Layout Service
- Available in 0.18μ, 0.13μ, 90nm, 65nm, 40nm & 28nm CMOS logic and mixed signal processes (MS/RF)

0.18μ G MS/RF	0.13μ G MS/RF	90nm LP and G	65nm LP and G MS/RF	40nm LP and G MS/	28nm CMOS RF HPC/HPC+ (1)	28nm CMOS RF HPL (1)
Nominal, Medium, Native VT Hipo resistor Mim Capacitor 3M—6M Al (1.8/3.3V) Triple well Ultra thick metal	SVT, HVT, LVT, native Hipo resistor MiM Capacitor 3M—8M Cu (1.2V) (2.5 or 3.3V IO) Triple Well Ultra thick metal	SVT, HVT, LVT, ULVT, native MiM Capacitor + MoM 3M—9M Cu Triple Well Ultra thick metal <u>LP</u> (1.2V) (2.5 or 3.3V) IO <u>G</u> (1.0V) (1.8 or 2.5V or 3.3V IO)	HVT, SVT, LVT, Native, m-low VT Unsilicided PO resistors MiM Capacitor 3M-9M Cu Triple well Ultra thick metal <u>LP</u> 1.2V (2.5, 3.3) IO <u>G</u> 1.0 (2.5, 3.3) IO	HVT, SVT, LVT, native NWELL, OD, Poly resistor MiM Capacitor 3M-9M Cu Triple well Ultra thick metal <u>LP</u> 1.2V (2.5, 3.3) IO <u>G</u> 1.0 (2.5, 3.3) IO	10 metals DNW 0.9V core NWELL, OD, Poly resistor MiM Capacitor 3M-10M ELK Cu Triple well Ultra thick metal <u>LP</u> 1.1V (IO 1.8V, 2.5V) <u>G</u> 0.9V (IO 1.8V, 2.5V)	10 metals DNW 1.0V core 1.8V I/O 2.5V I/O NW resistor OD resistor unsilicided High-R resistor Ultra Low Vt Low Vt Std Vt High Vt Ultra High Vt Extreme high Vt MOM capacitor UTM No Poly fuse

(1) Upon approval of TSMC

MPW runs in 2019	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
TSMC 0.18 CMOS Logic or Mixed-Signal/RF, General Purpose	30	20	6,27	17,24	8	5,12, 26	31	28		2,23	27	
TSMC 0.18 CMOS High Voltage BCD Gen II	9	20,27	28	17	1	5,12	3	7	4	2,30		4
TSMC 0.13 CMOS Logic or Mixed-Signal/RF, General Purpose or Low Power (8-inch)			13			5		28				4
TSMC 0.13 CMOS Logic or Mixed-Signal/RF, General Purpose or Low Power (12-inch)	9	13		10	15		10	14		9	13	
TSMC 90nm CMOS Logic or Mixed-Signal/RF, General Purpose or Low Power	2			17			10				2	
TSMC 65nm CMOS Logic or Mixed-Signal/RF, General Purpose or Low Power (reserve 4 months in advance)	30	20	27	24	22	26	24	28	25	23	27	
TSMC 40nm CMOS Logic or Mixed-Signal/RF, General Purpose or Low Power (no triple gate oxide)	2	6	6	10	1	5	3	7	4	9	6	4
TSMC 28nm CMOS Logic HPL/HPC/HPC+, RF HPL/HPC/HPC+ (reserve 4 months in advance)		6,27		3	1,29		3,31	28		2,30		4

Data in RED color are preliminary scheduled

All documentation & design kits available on:
For more information: mpc@imec.be

www.europactice-ic.com